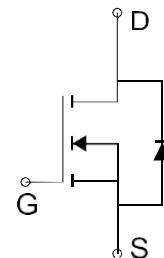


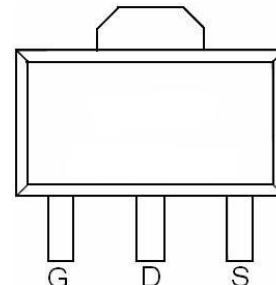
General Description:

The 5N10 is the single N-Channel logic enhancement mode power field effect transistors to provide excellent $R_{DS(on)}$, low gate charge and low gate resistance. It's up to 30V operation voltage is well suited in switching mode power supply, SMPS, notebook computer power management and other battery powered circuits.



Features:

- $R_{DS(ON)} < 125\text{m}\Omega$ @ $V_{GS} = 10\text{V}$ (N-Ch)
- $R_{DS(ON)} < 135\text{m}\Omega$ @ $V_{GS} = 4.5\text{V}$ (N-Ch)
- Super high density cell design for extremely low $R_{DS(ON)}$
- Exceptional on-resistance and maximum DC current



Applications:

- Switching power supply, SMPS
- Battery Powered System
- DC/DC Converter
- DC/AC Converter
- Load Switch

Table 1. Absolute Maximum Ratings ($T_A=25^\circ\text{C}$)

Symbol	Parameter	Value	Unit
VDS	Drain-Source Voltage ($V_{GS}=0\text{V}$)	100	V
VGS	Gate-Source Voltage ($V_{DS}=0\text{V}$)	± 25	V
I_D	Drain Current-Continuous($T_c=25^\circ\text{C}$)	5	A
	Drain Current-Continuous($T_c=100^\circ\text{C}$)	3.1	A
IDM (pulse)	Drain Current-Continuous@ Current-Pulsed (Note 1)	20	A
P_D	Maximum Power Dissipation	9.3	W
TJ,TSTG	Operating Junction and Storage Temperature Range	-55 To 150	$^\circ\text{C}$

Notes 1.Repetitive Rating: Pulse width limited by maximum junction temperature

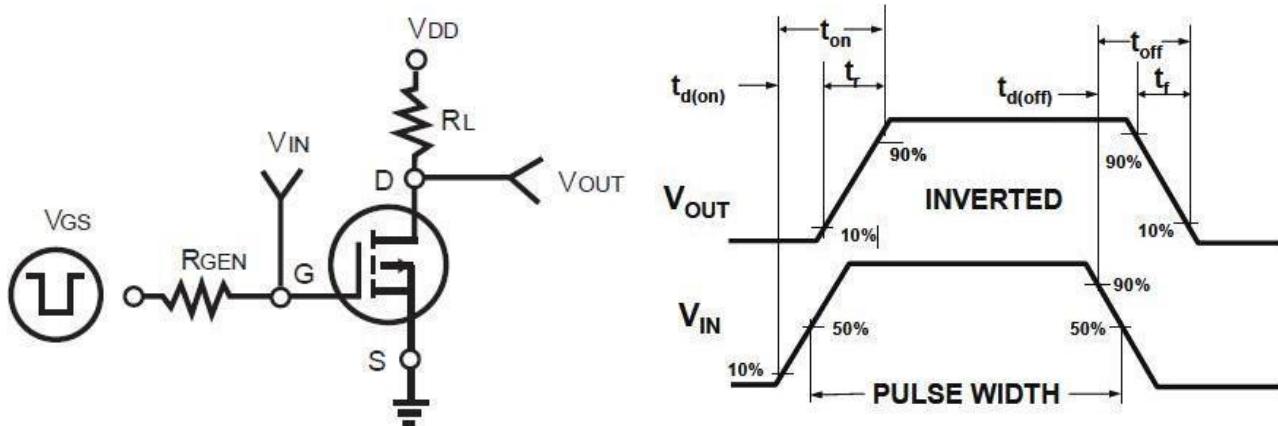
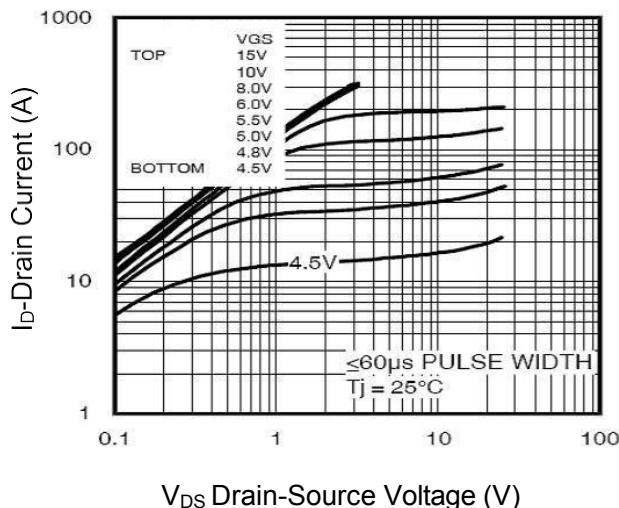
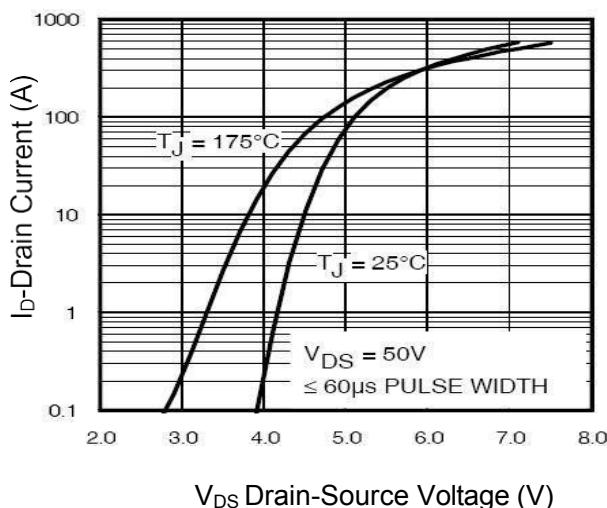
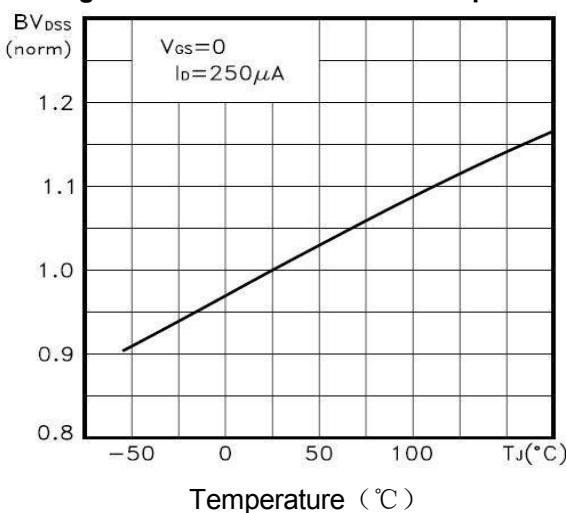
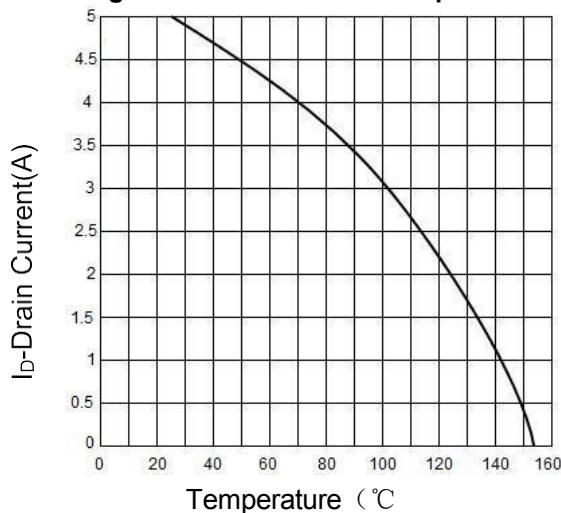
Table 2. Thermal Characteristic

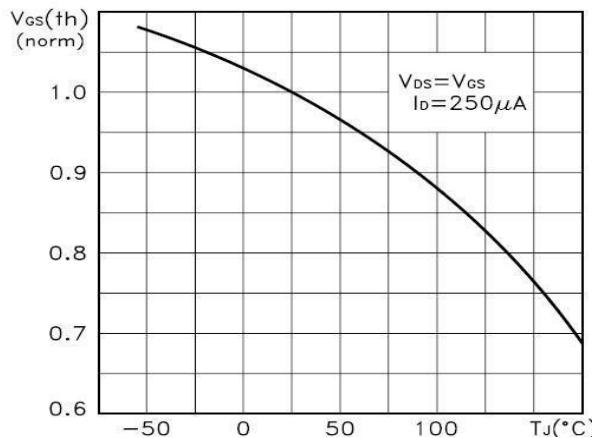
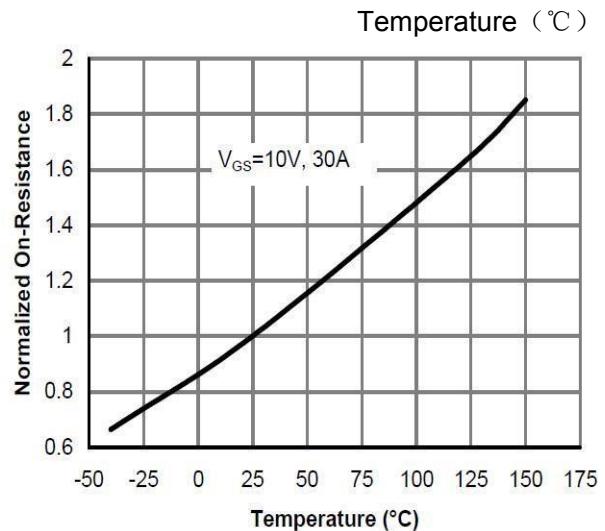
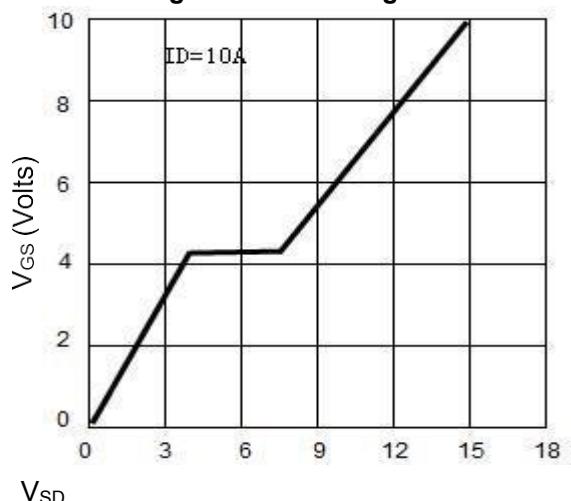
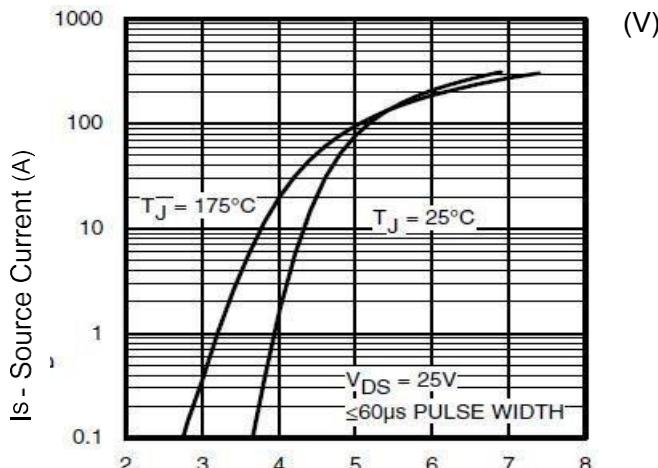
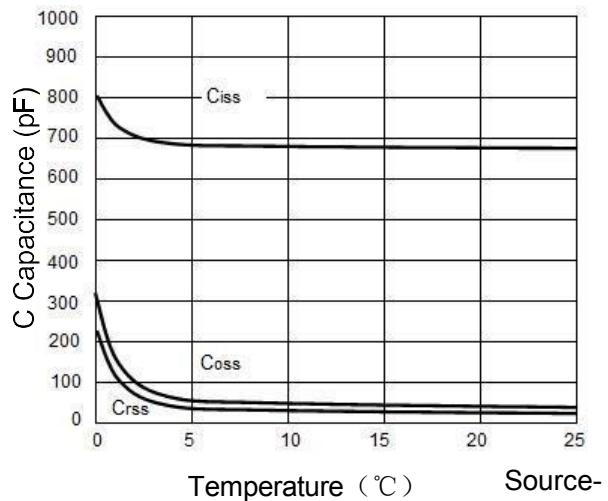
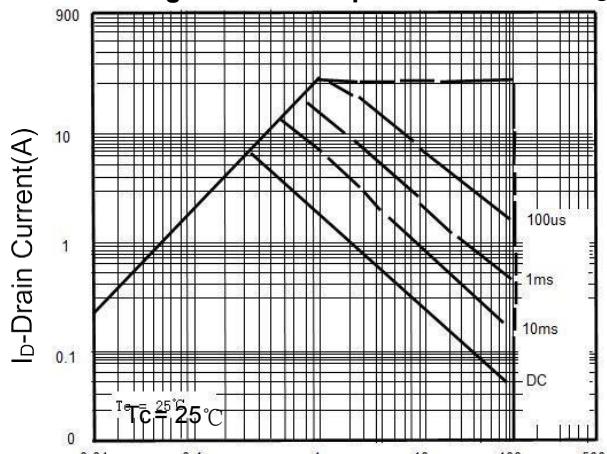
Symbol	Parameter	Type	Value	Unit
R_{JA}	Thermal Resistance, Junction-to-Ambient	-	13.5	$^\circ\text{C}/\text{W}$

Table 3. Electrical Characteristics ($T_A=25^\circ\text{C}$ unless otherwise noted)

Symbol	Parameter	Conditions	Min	Type	Max	Unit
On/Off States						
BV _{DSS}	Drain-Source Breakdown Voltage	V _{GS} =0V I _D =250μA	100			V
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} =100V, V _{GS} =0V			100	μA
I _{GSS}	Gate-Body Leakage Current	V _{GS} =±20V, V _{DS} =0V			±100	nA
V _{GS(th)}	Gate Threshold Voltage	V _{DS} =V _{GS} , I _D =250μA	1	1.5	3	V
R _{D(S)}	Drain-Source On-State Resistance	V _{GS} =10V, I _D = 10A		110	125	mΩ
		V _{GS} =4.5V, I _D =-5A		120	135	mΩ
Dynamic Characteristics						
C _{iss}	Input Capacitance	V _{DS} =25V, V _{GS} =0V, f=1.0MHz		690		pF
C _{oss}	Output Capacitance			120		pF
C _{rss}	Reverse Transfer Capacitance			90		pF
Switching Times						
t _{d(on)}	Turn-on Delay Time	V _{DD} =15V, I _D =1A, R _L =15V _{GS} =10V, R _G =2.5		11		ns
t _r	Turn-on Rise Time			7.4		ns
t _{d(off)}	Turn-Off Delay Time			35		ns
t _f	Turn-Off Fall Time			9.1		ns
Q _g	Total Gate Charge	V _{DS} =15V, I _D =10A V _{GS} =10V		15.5		nC
Q _{gs}	Gate-Source Charge			3.2		nC
Q _{gd}	Gate-Drain Charge			4.7		nC
Source-Drain Diode Characteristics						
I _{SD}	Source-Drain Current(Body Diode)				20	A
V _{SD}	Forward on Voltage (Note 1)	V _{GS} =0V, I _S =2A			0.8	V

Notes 1. Repetitive Rating: Pulse width limited by maximum junction temperature.

Switch Time Test Circuit and Switching Waveforms:

TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS (Curves)
Figure1. Output Characteristics

Figure2. Transfer Characteristics

Figure3. BVDSS vs Junction Temperature

Figure4. ID vs Junction Temperature


100V N-Channel Enhancement Mode MOSFET
Figure5. VGS(th) vs Junction Temperature

Figure6. Rdson Vs Junction Temperature

Figure7. Gate Charge

Figure9. Source-Drain Diode Forward
 Source-Drain Diode Forward Current (Is) versus Drain-Source Voltage (VDS)

Figure8. Capacitance vs Vds

Figure10. Safe Operation Area Voltage


100V N-Channel Enhancement Mode MOSFET
Figure11. Normalized Maximum Transient Thermal Impedance
